

S E R V I C E N O T E

SUPERSEDES: None

J2302B LAN Advisor

J2301B-07 Serial Numbers: EC Label less than EC:12
 J2302B-07 Serial Numbers: EC Label less than EC:11
 J2522B-07 Serial Numbers: EC Label less than EC:10
 J2523B-07 Serial Numbers: EC Label less than EC:10

Modifications to be made to all units shipped prior to EC label EC:11 to improve reliability

- 1: Floppy Disk Drive Isolation
- 2: CPU heat sink modification

Situation 1:

The Floppy Disk drive being mounting to ground is causing ground loops in the Internet Advisor B-series mainframes. The end result is intermittent FDD errors at power on and at time when the floppy disk drive is accessed. To correct this situation, the floppy disk drive needs to be isolated from the mounting brackets and the metal side chassis.

Solution 1:

Cut to fit and apply inch wide Teflon tape P.N. 0460-1678 to the inside of both floppy disk mounting brackets. Cut to fit and apply half inch wide Teflon tape P.N. 0460-2477 completely around the front of the floppy disk drive, right behind the plastic bezel. Replace the metal floppy disk mounting screws with plastic mounting screws P.N. 0515-2823.

Continued

DATE: June 1996

ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION:					
MODIFICATION RECOMMENDED					
ACTION CATEGORY:	<input type="checkbox"/> IMMEDIATELY <input type="checkbox"/> ON SPECIFIED FAILURE <input checked="" type="checkbox"/> AGREEABLE TIME	STANDARDS:	Labor 1.0 Hour		
LOCATION CATEGORY:	<input type="checkbox"/> CUSTOMER INSTALLABLE <input type="checkbox"/> ON-SITE <input checked="" type="checkbox"/> SERVICE CENTER	SERVICE INVENTORY:	<input type="checkbox"/> RETURN <input checked="" type="checkbox"/> SCRAP <input type="checkbox"/> SEE TEXT	USED PARTS:	<input type="checkbox"/> RETURN <input checked="" type="checkbox"/> SCRAP <input type="checkbox"/> SEE TEXT
AVAILABILITY:	PRODUCT'S SUPPORT LIFE		AGILENT RESPONSIBLE UNTIL: August 1998		
AUTHOR: RM	ENTITY: 3801	ADDITIONAL INFORMATION:			

Situation 2:

The heat sink that is mounted to the DOS CPU Microprocessor is touching a PEM nut on the bottom chassis. This shorting may cause RFI from the microprocessor to radiate through the chassis to the outside. This RFI radiation may also cause random failures of memory, floppy disk drives, and hard disk drives.

Solution 2:

To isolate the heat sink from this shorting potential you will need to clip off 4 fins of the heat sink. Refer to the following diagram to identify which fins to clip. Clip the fins that are indicated by the x's in the diagram.

```
                heat sink
0 0 0 0 0 0 0 0 0 0 0 0
0 0 0 0 0 0 0 x 0 0 0 0
0 0 0 0 0 0 x x x 0 0 0
( CMOS )
( battery )
(           )
```